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(12) **United States Design Patent**  
**Sugawara**

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(54) **PROCESS TUBE FOR MANUFACTURING SEMICONDUCTOR WAFERS**

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(73) Assignee: **Tokyo Electron Limited**, Tokyo (JP)

(\*\*) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Classification Search** ..... D13/182;  
D7/600.2, 701; D23/266; 83/35, 39; 118/715;  
138/92, 118, 118.1, 121, 178; 206/454, 711;  
211/41.18; 414/935; 432/253

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a process tube for manufacturing semiconductor wafers, as shown and described.

**DESCRIPTION**

FIG. 1 is a reference perspective view of the process tube for manufacturing semiconductor wafers;

FIG. 2 is a reference perspective view of the process tube as seen from another direction;

FIG. 3 is a front view of the process tube;

FIG. 4 is a back view thereof;

FIG. 5 is a left side view thereof. A right side view thereof is a mirror image thereto;

FIG. 6 is a top view thereof;

FIG. 7 is a bottom view thereof;

FIG. 8 is a sectional view taken along line 8—8 in FIG. 6; and,

FIG. 9 is a sectional view taken along line 9—9 in FIG. 3.

**1 Claim, 4 Drawing Sheets**

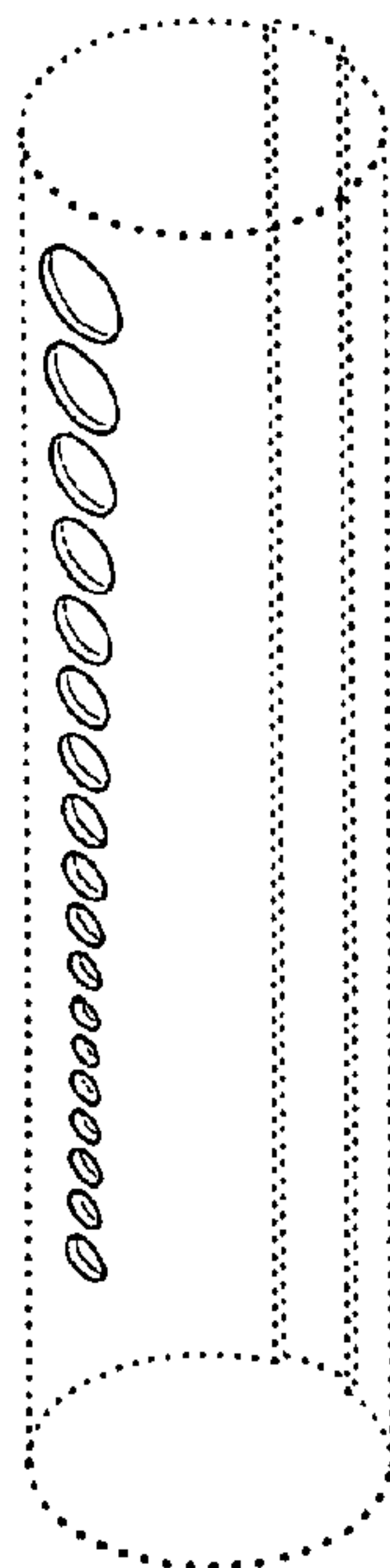


FIG. 1

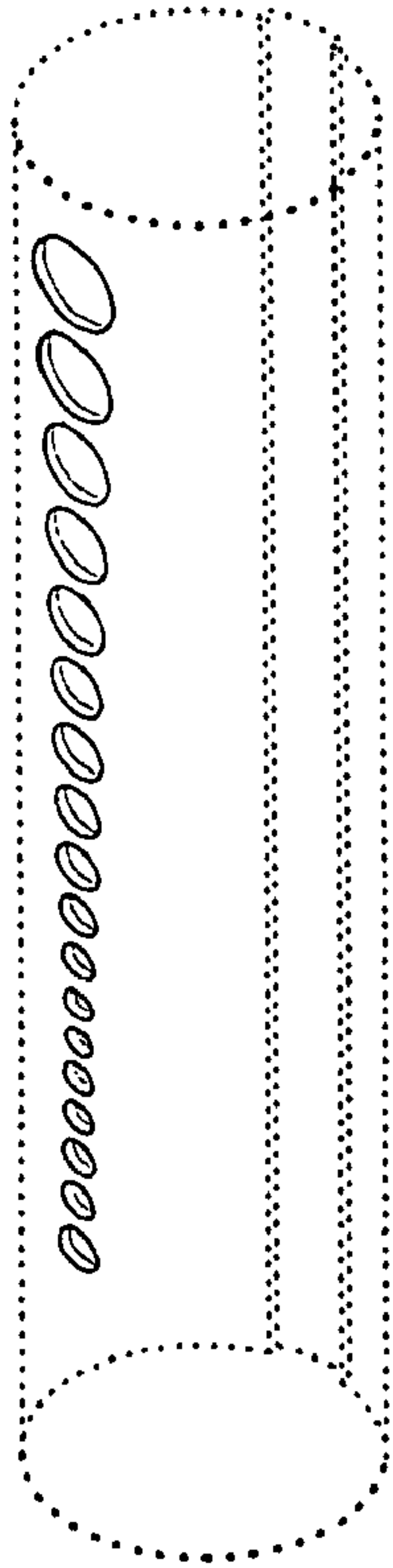


FIG. 2

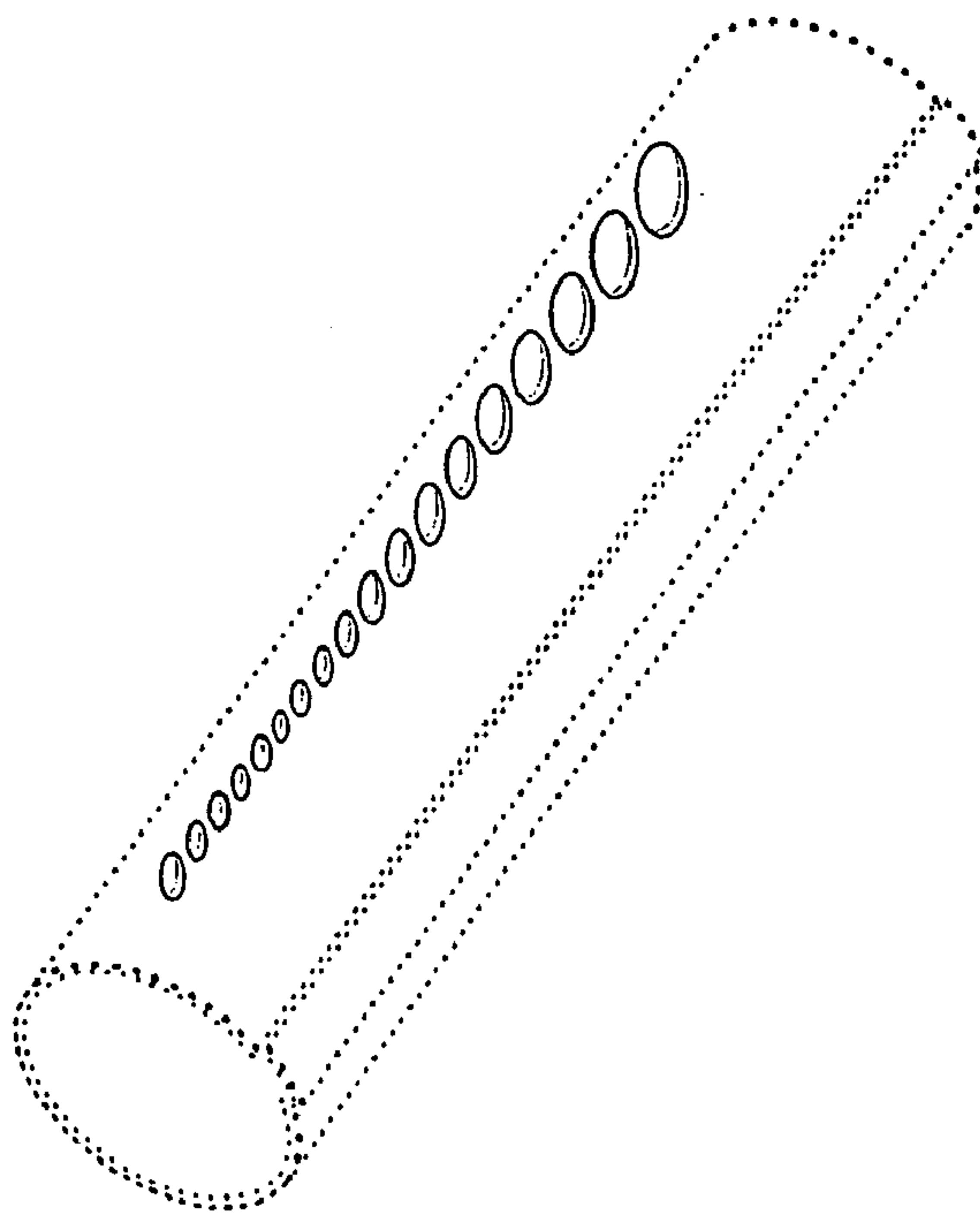


FIG. 3

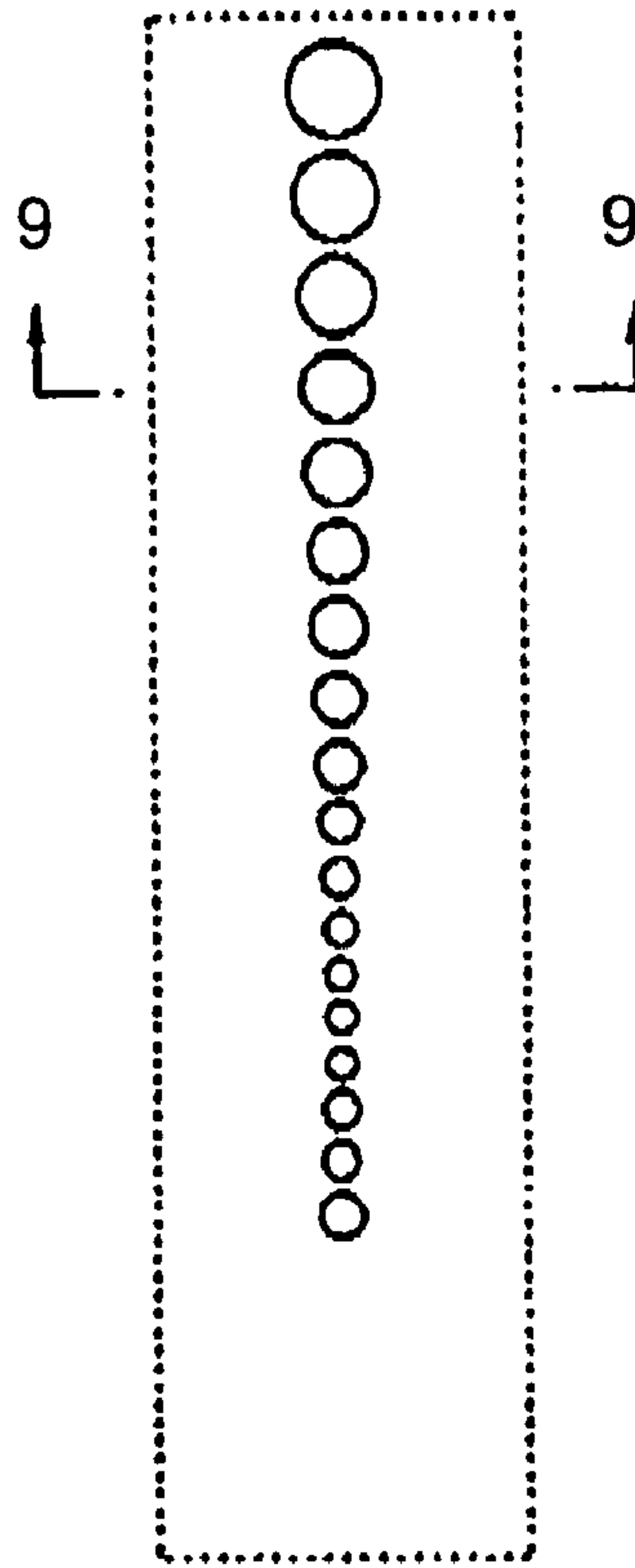


FIG. 4

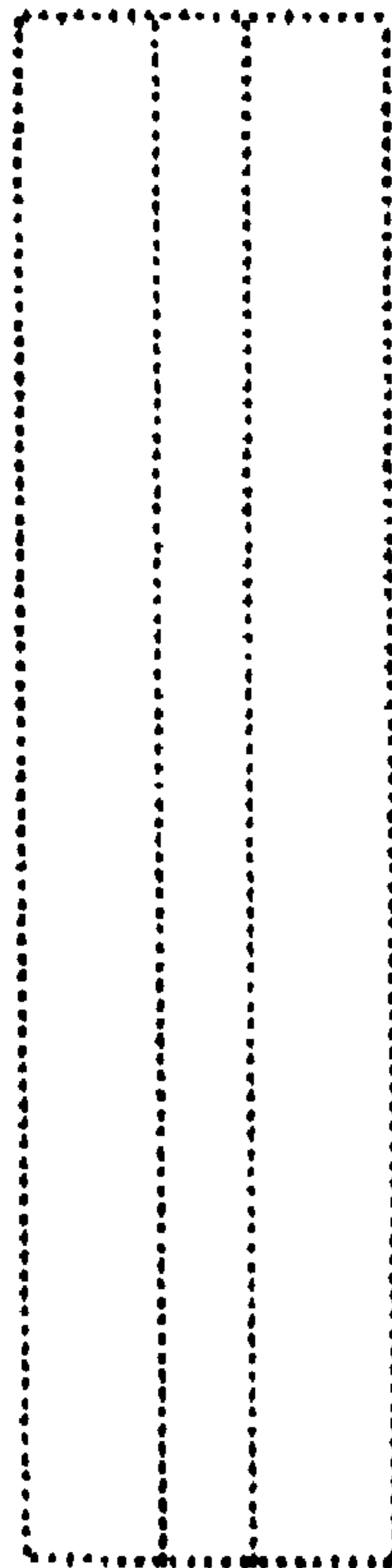


FIG. 5

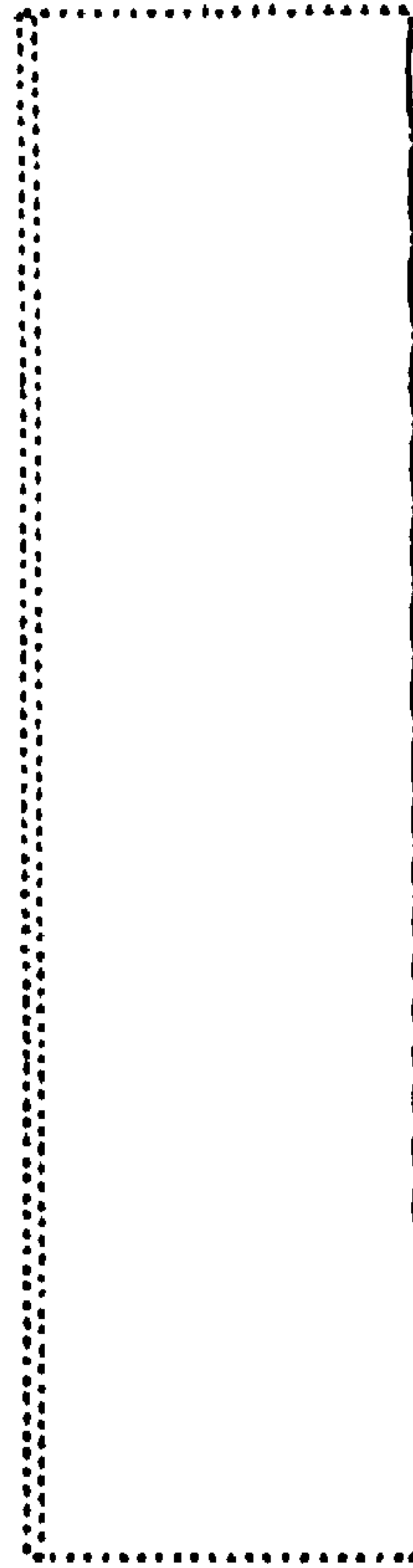


FIG. 6

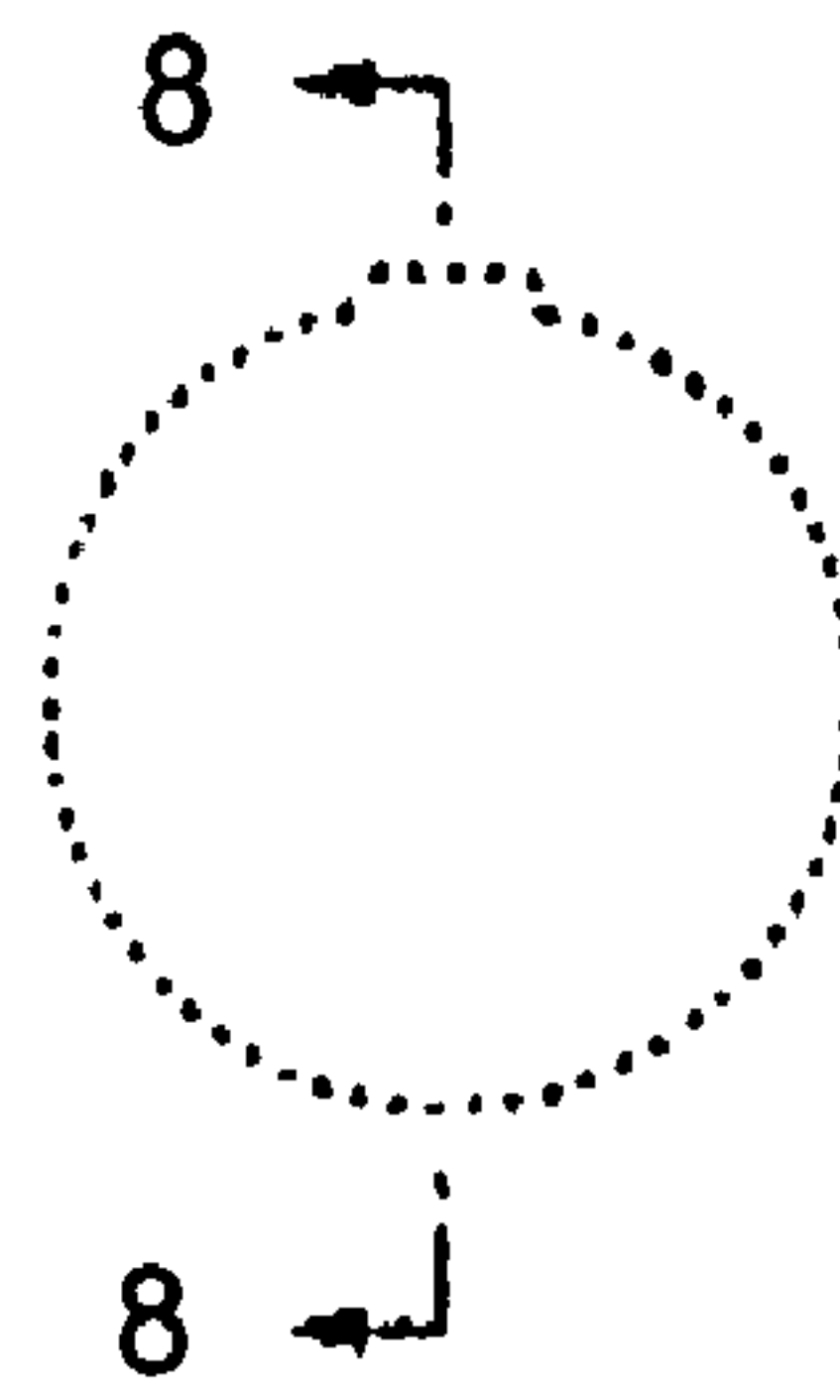


FIG. 7

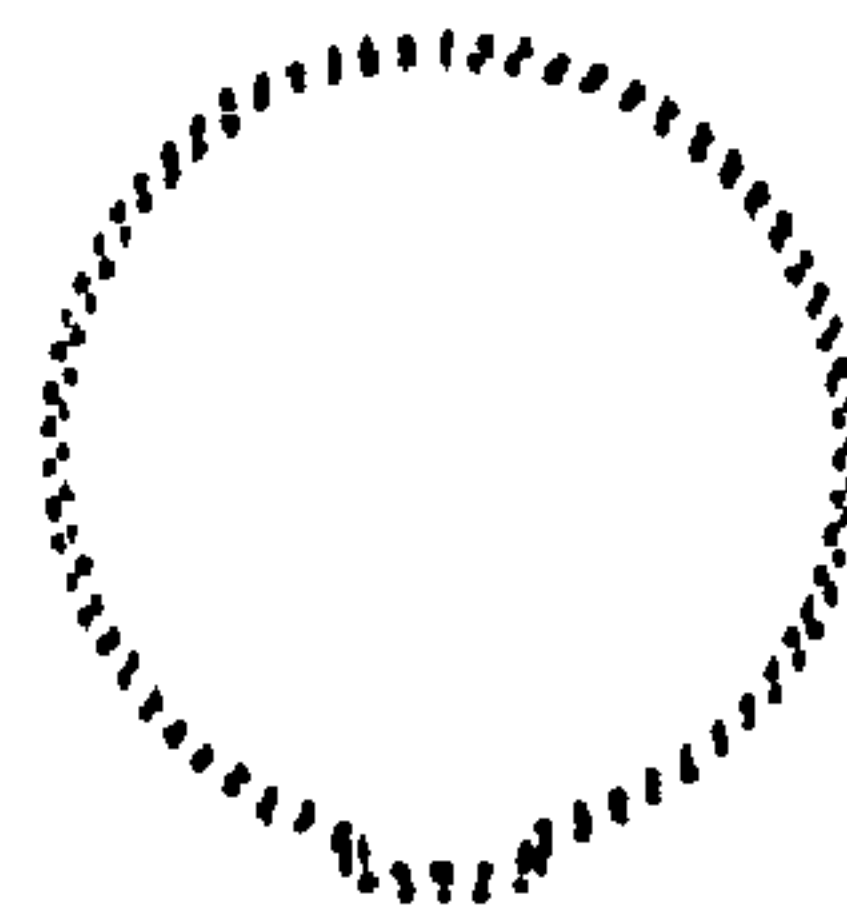


FIG. 8

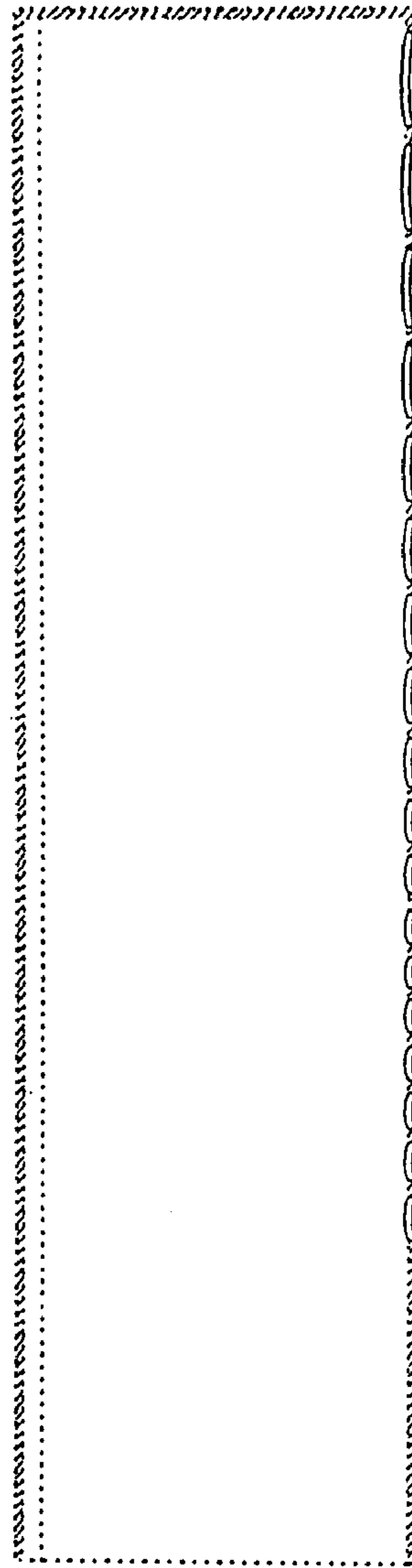


FIG. 9

